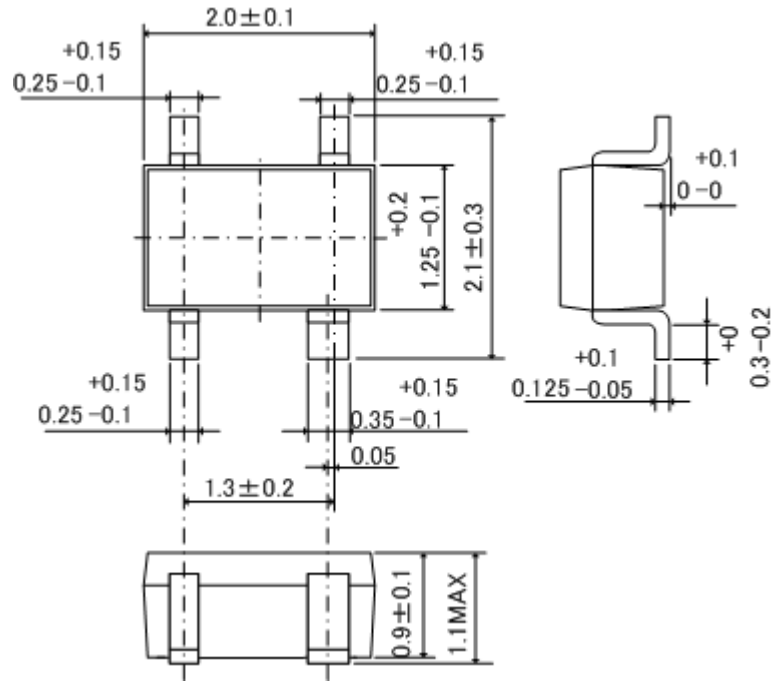


Packaging Information / Reference Pattern Layout Dimensions

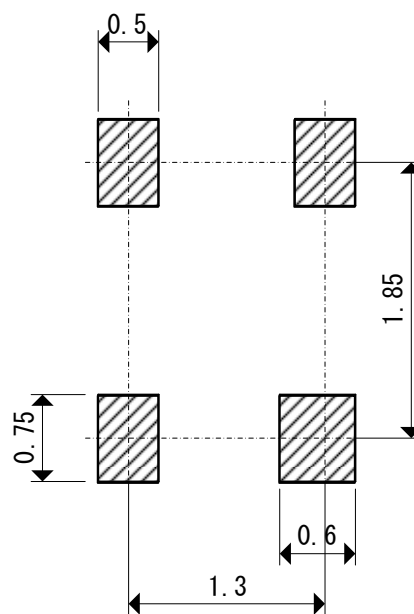
● SSOT-24

Unit: mm

■ Packaging Information



■ Reference Pattern Layout Dimension

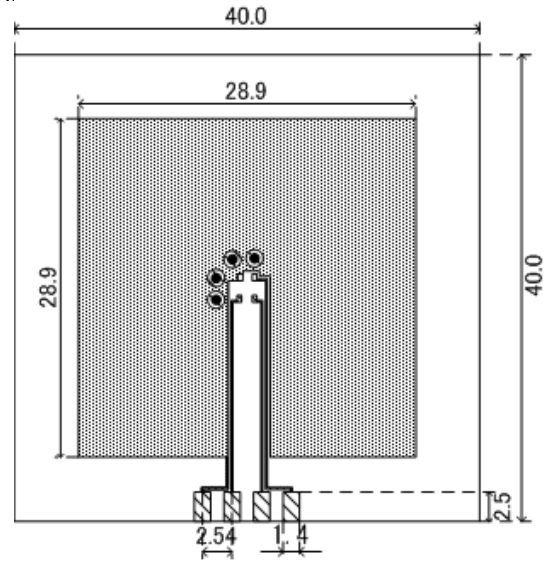


●SSOT-24 Power Dissipation

Power dissipation data for the SSOT-24 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as the reference data taken in the following condition.



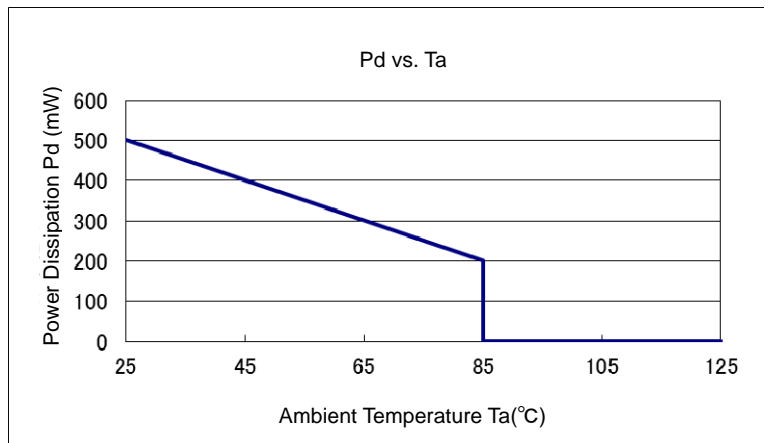
Evaluation Board (Unit: mm)

- Condition: Mount on a board
- Ambient: Natural convection
- Soldering: Lead (Pb) free
- Board: Dimensions 40 x 40 mm (1600 mm² in one side)
- Copper (Cu) traces occupy 50% of the board area
- In top and back faces
- Package heat-sink is tied to the copper traces
- Material: Glass Epoxy (FR-4)
- Thickness: 1.6 mm
- Through-hole: 4 x 0.8 Diameter

2. Power Dissipation vs. Ambient Temperature (85°C)

Board Mount (T_{jmax}=125°C)

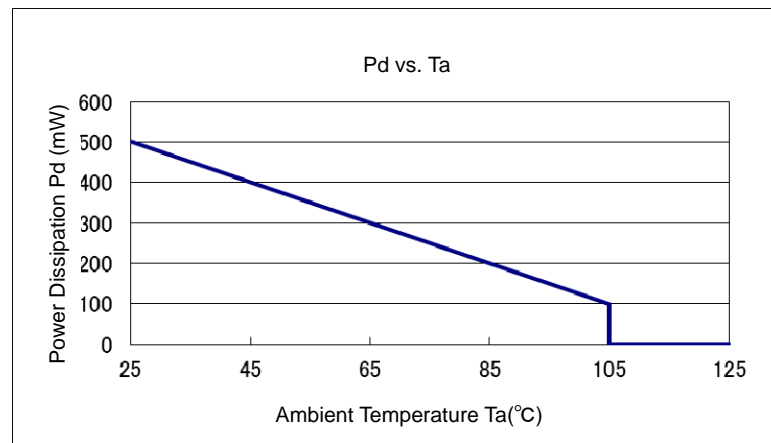
Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	500	200.00
85	200	



3. Power Dissipation vs. Ambient Temperature (105°C)

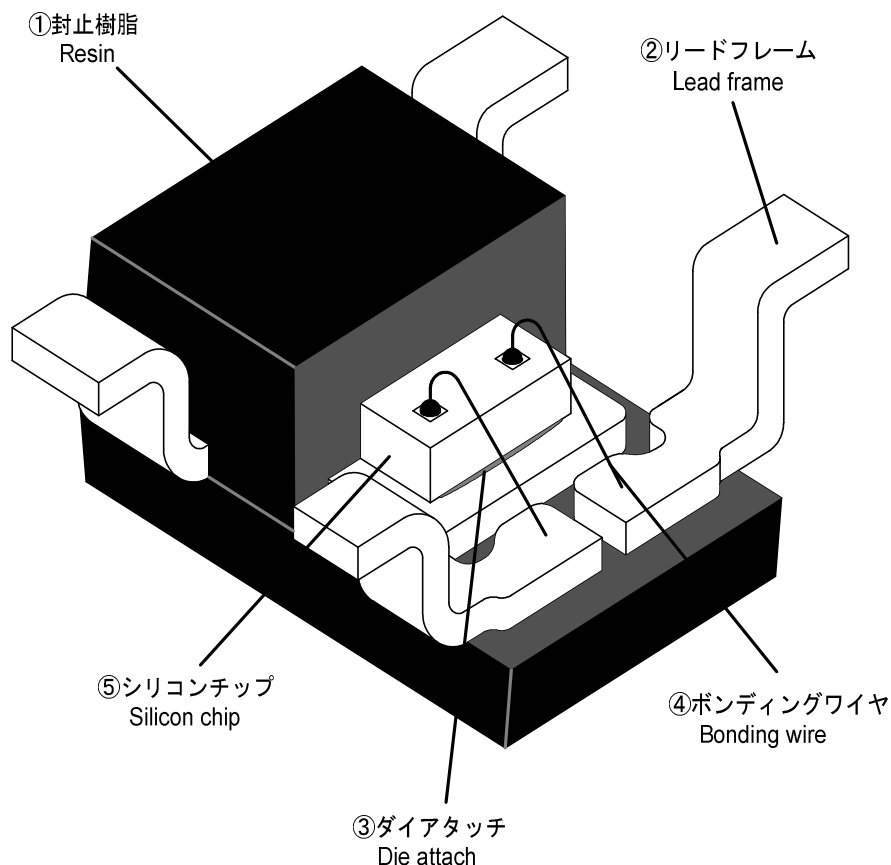
Board Mount (T_{jmax}=125°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	500	200.00
85	100	



SSOT-24 構造図 SSOT-24 Perspective

RoHS対応品
RoHS Compliance



項目 Item	材料 Material	備考 Note
① 封止樹脂 Resin	エポキシ樹脂 Epoxy resin	難燃グレード/Flammability rating UL94V-0
② リードフレーム Lead frame	銅系 Copper alloy	
端子処理 Lead plating	鉛フリーはんだメッキ Lead(Pb) free solder plating	
③ ダイアタッチ Die attach	エポキシ Epoxy	
④ ボンディングワイヤ Bonding wire	Au	
⑤ シリコンチップ Silicon chip	Si	

捺印表示 Marking	レーザー Laser marking
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